



RE460

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au and solder stop mask
- Pitches from 0.50 to 1.27 mm
- Hole diameter 1.00 mm
- Adaption board for 23 different SMD-IC's
- Prescratched rated break point for the separation of individual modules from the board
- Manual soldering: as for the SMD individual processing in the laboratory area, a freehanded coating of 100 to 200 single spots with precise metering hoppers is possible with grids from 0.50 to 1.27 mm
- Reflow soldering by means of purpose made separate SMD templates
- Size 120 x 175 mm

Module-No.	Pitch	Pin
RE460-01	0.800 mm	QFP 32, 80
	0.500 mm	QFP 64
RE460-02	0.800 mm	QFP 80
	0.650 mm	QFP 100
RE460-03	0.650 mm	QFP 80, 84
RE460-04	0.650 mm	QFP 144, 160
	0.635 mm	QFP 100, 132, 164
RE460-05	1.270 mm	PLCC 32, 52, 68, 84
	0.635 mm	QFP 100
	0.500 mm	QFP 100
RE460-06	1.270 mm	PLCC 28, 44
	0.800 mm	QFP 44
RE460-07	1.270 mm	PLCC 18
RE460-08	1.270 mm	PLCC 20
RE460-09	1.270 mm	PLCC-Eprom 32